

Switch-mode Power Rectifier

DPAK Surface Mount Package

MURD620CT, NRVUD620CT, SRVUD620CT, SNRVUD620CT

These state-of-the-art devices are designed for use in switching power supplies, inverters and as free wheeling diodes.

Features

- Ultrafast 35 Nanosecond Recovery Time
- Low Forward Voltage Drop
- Low Leakage
- ESD Rating:
 - ♦ Human Body Model = 3B (> 8 kV)
 - ♦ Machine Model = C (> 400 V)
- NRVUD, SRVUD and SNRVUD Prefixes for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

Mechanical Characteristics:

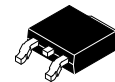
- Case: Epoxy, Molded
- Weight: 0.4 Gram (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds



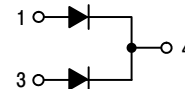
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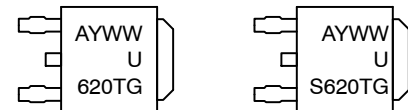
ULTRAFAST RECTIFIER 6.0 AMPERES 200 VOLTS



DPAK
CASE 369C



MARKING DIAGRAMS



A = Assembly Location*
Y = Year
WW = Work Week
U620T = Device Code (MURD/NRVUD/
SNRVUD620CT)
US620T = Device Code (SRVUD620CT)
G = Pb-Free Package

* The Assembly Location Code (A) is front side optional. In cases where the Assembly Location is stamped in the package bottom (molding ejector pin), the front side assembly code may be blank.

ORDERING INFORMATION

Device	Package	Shipping†
MURD620CTG	DPAK (Pb-Free)	75 Units / Rail
NRVUD620CTG	DPAK (Pb-Free)	75 Units / Rail
MURD620CTT4G	DPAK (Pb-Free)	2,500 / Tape & Reel
NRVUD620CTT4G	DPAK (Pb-Free)	2,500 / Tape & Reel
SRVUD620CTT4G	DPAK (Pb-Free)	2,500 / Tape & Reel
SNRVUD620CTT4G	DPAK (Pb-Free)	2,500 / Tape & Reel
NRVUD620CTG-VF01	DPAK (Pb-Free)	2,500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MURD620CT, NRVUD620CT, SRVUD620CT, SNRVUD620CT

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	200	V
Average Rectified Forward Current ($T_C = 140^\circ\text{C}$) Per Diode Per Device	$I_{F(AV)}$	3.0 6.0	A
Peak Repetitive Forward Current (Square Wave, Duty = 0.5, $T_C = 145^\circ\text{C}$) Per Diode	I_F	6.0	A
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, 60 Hz)	I_{FSM}	50	A
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-65 to +175	$^\circ\text{C}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS (Per Diode)

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	9	$^\circ\text{C/W}$
Thermal Resistance, Junction-to-Ambient (Note 1)	$R_{\theta JA}$	80	$^\circ\text{C/W}$

1. Rating applies when surface mounted on the minimum pad sizes recommended.

ELECTRICAL CHARACTERISTICS (Per Diode)

Characteristic	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage Drop (Note 2) ($I_F = 3$ Amps, $T_C = 25^\circ\text{C}$) ($I_F = 3$ Amps, $T_C = 125^\circ\text{C}$) ($I_F = 6$ Amps, $T_C = 25^\circ\text{C}$) ($I_F = 6$ Amps, $T_C = 125^\circ\text{C}$)	V_F	1 0.96 1.2 1.13	V
Maximum Instantaneous Reverse Current (Note 2) ($T_J = 25^\circ\text{C}$, Rated dc Voltage) ($T_J = 125^\circ\text{C}$, Rated dc Voltage)	i_R	5 250	μA
Maximum Reverse Recovery Time ($I_F = 1$ Amp, $di/dt = 50$ Amps/ μs , $V_R = 30$ V, $T_J = 25^\circ\text{C}$) ($I_F = 0.5$ Amp, $i_R = 1$ Amp, $I_{REC} = 0.25$ A, $V_R = 30$ V, $T_J = 25^\circ\text{C}$)	t_{rr}	35 25	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

2. Pulse Test: Pulse Width = 300 μs , Duty Cycle $\leq 2.0\%$.

TYPICAL CHARACTERISTICS

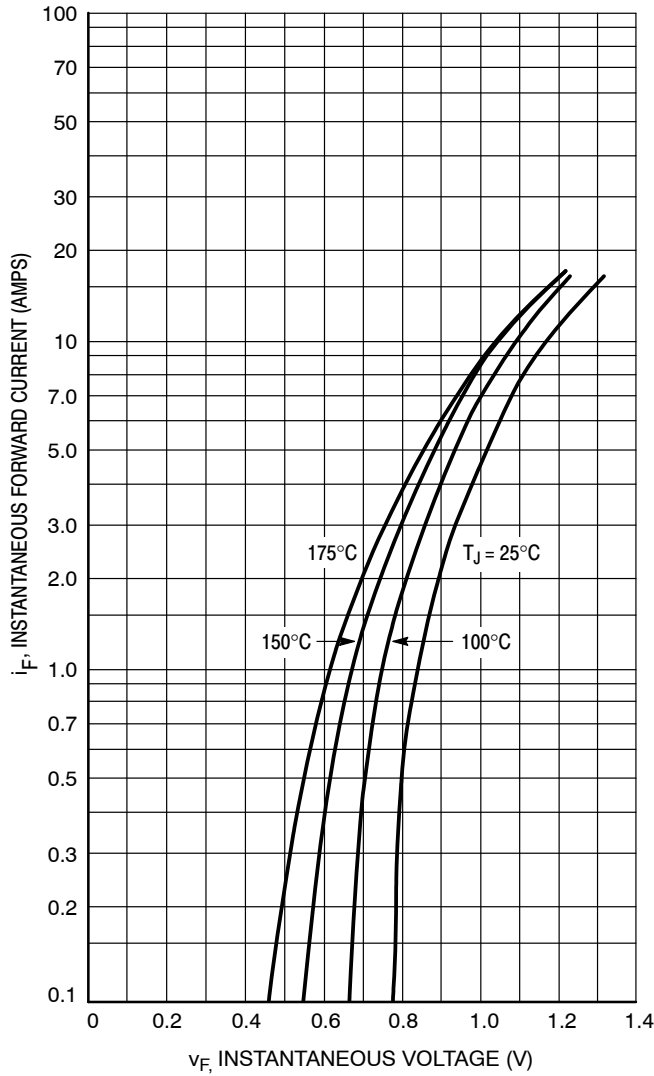


Figure 1. Typical Forward Voltage (Per Leg)

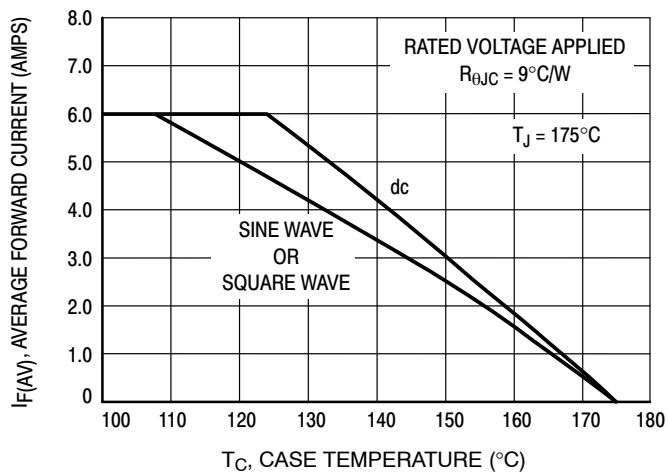


Figure 4. Current Derating, Case (Per Leg)

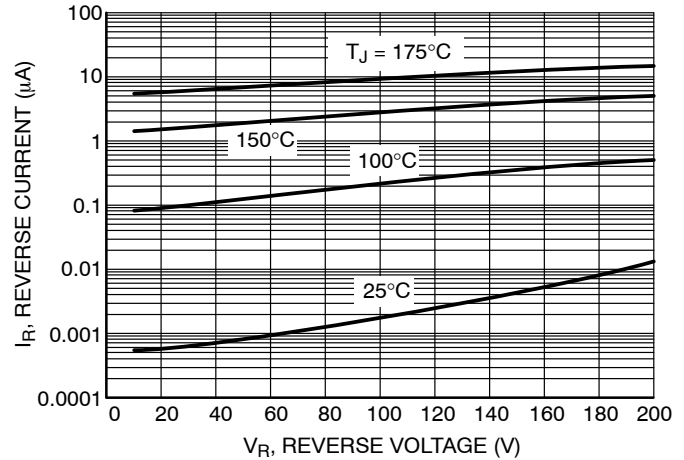


Figure 2. Typical Leakage Current* (Per Leg)

* The curves shown are typical for the highest voltage device in the voltage grouping. Typical reverse current for lower voltage selections can be estimated from these curves if V_R is sufficiently below rated V_R .

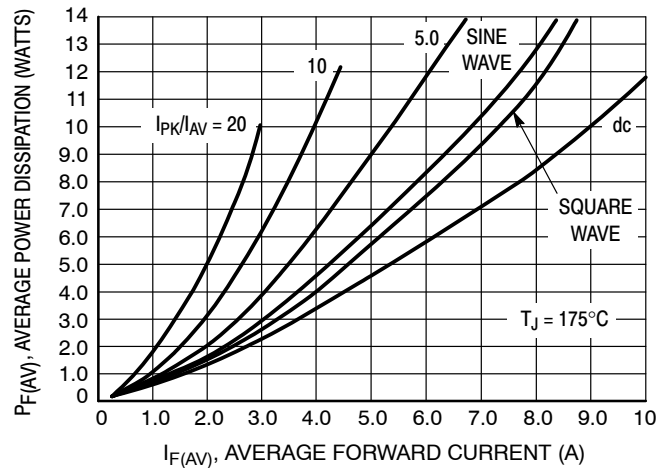


Figure 3. Average Power Dissipation (Per Leg)

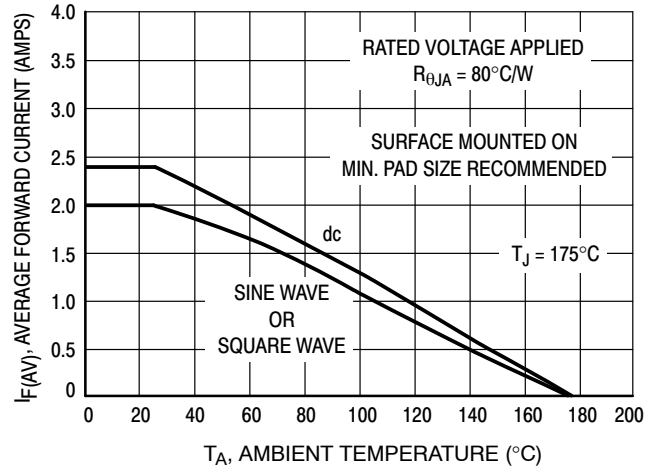


Figure 5. Current Derating, Ambient (Per Leg)

TYPICAL CHARACTERISTICS

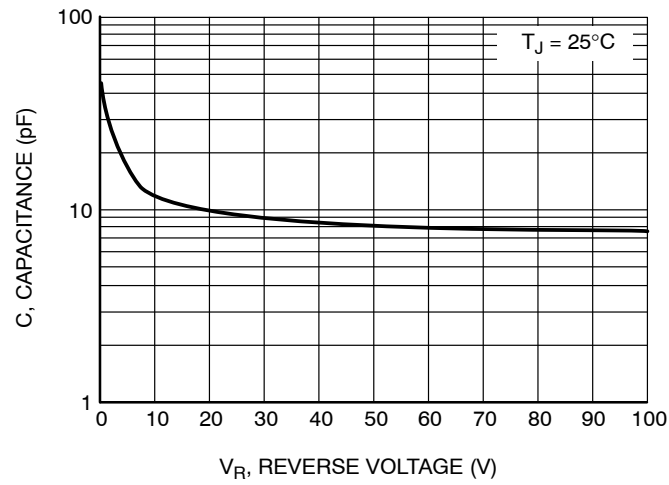
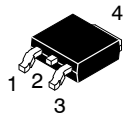


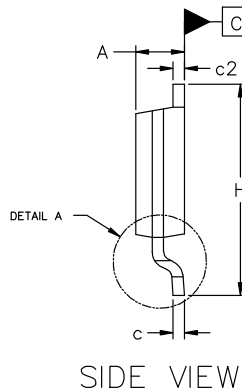
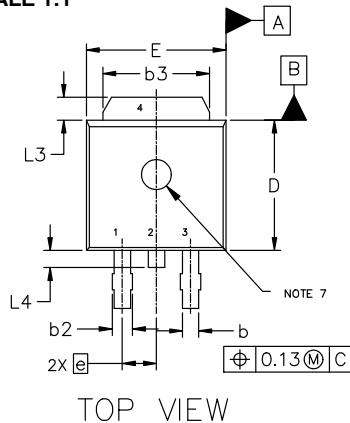
Figure 6. Typical Capacitance (Per Leg)



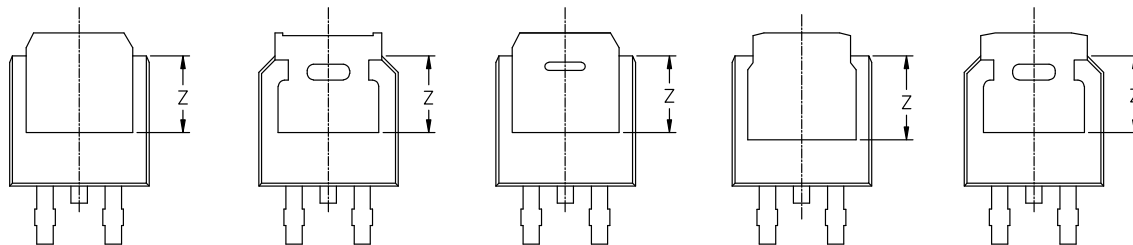
DPAK3 6.10x6.54x2.28, 2.29P
CASE 369C
ISSUE H

DATE 15 JUL 2025

SCALE 1:1

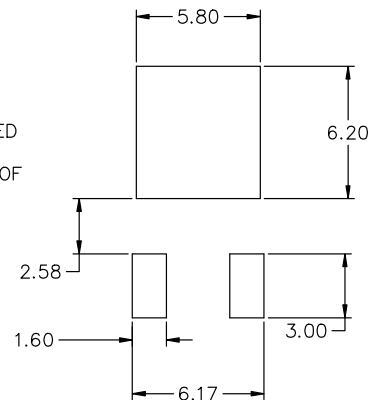
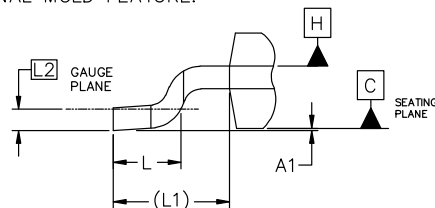


MILLIMETERS			
DIM	MIN	NOM	MAX
A	2.18	2.28	2.38
A1	0.00	---	0.13
b	0.63	0.76	0.89
b2	0.72	0.93	1.14
b3	4.57	5.02	5.46
c	0.46	0.54	0.61
c2	0.46	0.54	0.61
D	5.97	6.10	6.22
E	6.35	6.54	6.73
e	2.29 BSC		
H	9.40	9.91	10.41
L	1.40	10.10	1.78
L1	2.90 REF		
L2	0.51 BSC		
L3	0.89	---	1.27
L4	---	---	1.01
Z	3.93	---	---



NOTES:

1. DIMENSIONING AND TOLERANCING ASME Y14.5M, 2018.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3, L3, AND Z.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15mm PER SIDE.
5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
6. DATUMS A AND B ARE DETERMINED AT DATUM PLANE H.
7. OPTIONAL MOLD FEATURE.



RECOMMENDED MOUNTING FOOTPRINT*

*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ONSEMI SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

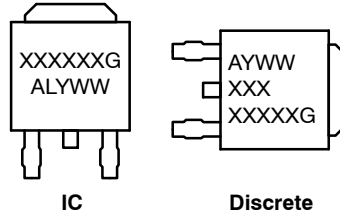
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DPAK3 6.10x6.54x2.28, 2.29P
CASE 369C
ISSUE H

DATE 15 JUL 2025

**GENERIC
MARKING DIAGRAM***



XXXXXX = Device Code
A = Assembly Location
L = Wafer Lot
Y = Year
WW = Work Week
G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

STYLE 1: PIN 1. BASE 2. COLLECTOR 3. EMITTER 4. COLLECTOR	STYLE 2: PIN 1. GATE 2. DRAIN 3. SOURCE 4. DRAIN	STYLE 3: PIN 1. ANODE 2. CATHODE 3. ANODE 4. CATHODE	STYLE 4: PIN 1. CATHODE 2. ANODE 3. GATE 4. ANODE	STYLE 5: PIN 1. GATE 2. ANODE 3. CATHODE 4. ANODE
STYLE 6: PIN 1. MT1 2. MT2 3. GATE 4. MT2	STYLE 7: PIN 1. GATE 2. COLLECTOR 3. EMITTER 4. COLLECTOR	STYLE 8: PIN 1. N/C 2. CATHODE 3. ANODE 4. CATHODE	STYLE 9: PIN 1. ANODE 2. CATHODE 3. RESISTOR ADJUST 4. CATHODE	STYLE 10: PIN 1. CATHODE 2. ANODE 3. CATHODE 4. ANODE

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